

TDEL1G533 Single Momentary Switch Interface

1 Features

- 1% typical, 10% maximum delay variation
- Pre-configured digital timing - no external timing components required
- Wide operating range from 1.65V to 5.5V
- I/O clamp diodes protect from over- and under-voltage transients
- Schmitt-trigger architecture on all inputs

2 Applications

- [Battery pack: cordless power tool](#)
- [Robotic lawn mower](#)
- [Industrial robot](#)
- [Digital multimeter \(DMM\)](#)
- Power control with momentary switch
- Robot kill switch with reset
- Medical equipment power control

3 Description

The TDEL1G533 is a power button controller that simplifies the implementation of momentary switches in a wide variety of electronic systems.

The TDEL1G533 offers multiple configurations with separate inputs for switches connected to either the positive voltage supply or ground. When either trigger input is activated (T for pull-up switches and $\bar{T}$ for pull-down switches), the output latches on and remains stable as long as power is applied. Holding either input active for more than 2 seconds causes the output to latch off. An inverted output is also

provided, always in the opposite state of the standard output. Additionally, a pass-through output delivers a debounced version of the input signals.

Regardless of the input signal type (active-high or active-low), the pass-through output always provides an active-high signal with a 100ms falling-edge delay. The open-drain pass-through circuit enables independent power supplies for the primary functionality and pass-through output, a common requirement for systems powered by a battery (such as 4.2V) where the pass-through signal must be read by a microcontroller operating at 3.3V or 1.8V.

Package Information

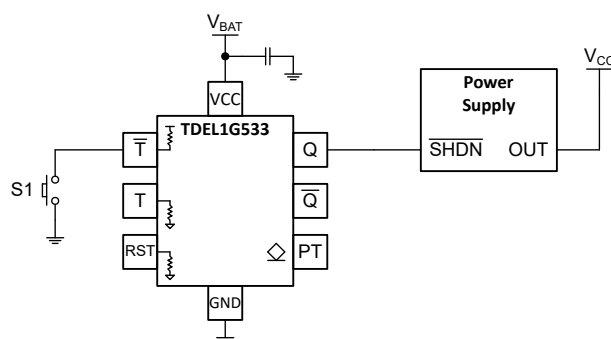
PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾	BODY SIZE ⁽³⁾
TDEL1G533	DRL (SOT-5X3, 8)	2.1mm × 1.6mm	2.1mm × 1.6mm

- (1) For all available packages, see the orderable addendum at the end of the datasheet.
- (2) The package size (length × width) is a nominal value and includes pins, where applicable.
- (3) The body size (length × width) is a nominal value and does not include pins.

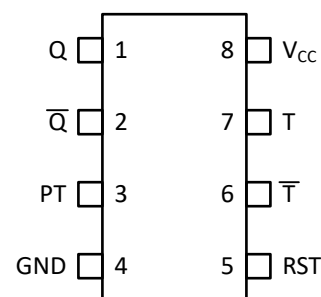
Device Information

PART NUMBER	DELAY TIME ⁽¹⁾	
	DEBOUNCE	SHUT-DOWN
TDEL1G51000	100ms	2s

- (1) Approximate values shown; see *Typical Characteristics* section for details



Functional Block Diagram



Pinout Diagram



Table of Contents

1 Features	1	7.4 Device Functional Modes.....	16
2 Applications	1	8 Application and Implementation	17
3 Description	1	8.1 Application Information.....	17
4 Pin Configuration and Functions	3	8.2 Typical Application.....	17
5 Specifications	4	8.3 Power Supply Recommendations.....	20
5.1 Absolute Maximum Ratings.....	4	8.4 Layout.....	20
5.2 ESD Ratings.....	4	9 Device and Documentation Support	22
5.3 Recommended Operating Conditions.....	4	9.1 Device Support.....	22
5.4 Thermal Information.....	5	9.2 Documentation Support.....	22
5.5 Electrical Characteristics.....	5	9.3 Receiving Notification of Documentation Updates....	22
5.6 Timing Characteristics.....	6	9.4 Support Resources.....	22
5.7 Switching Characteristics.....	7	9.5 Trademarks.....	22
5.8 Typical Characteristics.....	9	9.6 Electrostatic Discharge Caution.....	22
6 Parameter Measurement Information	10	9.7 Glossary.....	22
7 Detailed Description	12	10 Revision History	22
7.1 Overview.....	12	11 Mechanical, Packaging, and Orderable Information	24
7.2 Functional Block Diagram.....	12		
7.3 Feature Description.....	13		

4 Pin Configuration and Functions

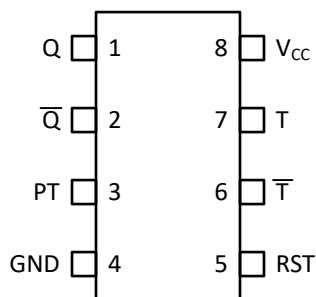


Figure 4-1. TDEL1G533 DRL Package (Top View)

Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	DRL NO.		
Q	1	O	Latching output, active-high
$\overline{Q}$	2	O	Latching output, active-low
PT	3	O	Pass-through output; open-drain
GND	4	G	Ground
RST	5	I	Reset input, active-high
$\overline{T}$	6	I	Active-low input; internal 1M Ω pull-up resistor
T	7	I	Active-high input; internal 1M Ω pull-down resistor
V_{CC}	8	P	Positive supply

(1) Signal Types: I = Input, O = Output, G = Ground, P = Power.

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		−0.5	6.5	V
V_I	Digital input voltage range ⁽²⁾		−0.5	$V_{CC} + 0.5$	V
V_O	Digital output voltage range ⁽²⁾		−0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp diode current, continuous	$V_I < -0.5V$ or $V_I > V_{CC} + 0.5$		±20	mA
	Input clamp diode current, pulsed 1μs	$V_I < -0.5V$ or $V_I > V_{CC} + 0.5$		±200	mA
I_{OK}	Output clamp diode current, continuous	$V_I < -0.5V$ or $V_I > V_{CC} + 0.5$		±20	mA
	Output clamp diode current, pulsed 1μs	$V_I < -0.5V$ or $V_I > V_{CC} + 0.5$		±200	mA
I_O	Digital output current, continuous	$V_O = 0$ to V_{CC}		±20	mA
	Digital output current, pulsed 1μs	$V_O = 0$ to V_{CC}		±100	mA
	Continuous current through V_{CC} or GND			±60	mA
T_J	Junction temperature			150	°C
T_{stg}	Storage temperature		−65	150	°C

- (1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. Absolute maximum ratings do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If briefly operating outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not sustain damage, but it may not be fully functional. Operating the device in this manner may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) The voltage ratings may be exceeded if the associated clamp current ratings are observed.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
		Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002 ⁽²⁾	±1000	

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		1.65	5.5	V
V_I	Input Voltage ⁽¹⁾		0	V_{CC}	V
V_O	Output Voltage		0	V_{CC}	V
I_{OH} ⁽²⁾	High-level output current	$V_{CC} = 1.65V$ to $2.2V$		−6	mA
		$V_{CC} = 2.3V$ to $5.5V$		−20	mA
I_{OL} ⁽²⁾	Low-level output current	$V_{CC} = 1.65V$ to $5.5V$		20	mA
C_L	Digital output load capacitance	$V_{CC} = 1.65V$ to $5.5V$		50	pF
V_{POR}	Power-on reset ramp voltage	$\Delta t/\Delta V_{CC} \geq 20\mu s/V$	0.3	1.5	V
$\Delta t/\Delta V_{CC}$	Power-on ramp rate	$V_{CC} = 0.3V$ to $1.5V$	20		μs/V
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 1.65V$ to $5.5V$		100	ms/V

5.3 Recommended Operating Conditions (continued)

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
T_A	Operating free-air temperature	-40	125	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.
- (2) Recommended maximum output current for continuous operation; see *Electrical Characteristics* for test current values to maintain V_{OH} and V_{OL} specifications. Operating with average output current greater than 12mA may impact device reliability and shorten the device lifetime.

5.4 Thermal Information

PACKAGE	PINS	THERMAL METRIC ⁽¹⁾						UNIT
		$R_{\theta JA}$	$R_{\theta JC(top)}$	$R_{\theta JB}$	Ψ_{JT}	Ψ_{JB}	$R_{\theta JC(bot)}$	
DRL (SOT-5X3)	8	118.4	77.1	26.5	3.9	25.9	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application note.

5.5 Electrical Characteristics

Over operating free-air temperature range; typical values measured at $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
V_{T+}	Positive switching threshold		1.65V	0.84	1.02	1.21	V
			1.8V	0.91	1.11	1.31	
			2.5V	1.24	1.48	1.72	
			3.3V	1.59	1.85	2.13	
			5V	2.29	2.65	3.03	
			5.5V	2.5	2.88	3.3	
V_{T-}	Negative switching threshold		1.65V	0.51	0.67	0.85	V
			1.8V	0.58	0.74	0.93	
			2.5V	0.88	1.07	1.29	
			3.3V	1.19	1.42	1.68	
			5V	1.8	2.11	2.47	
			5.5V	1.99	2.32	2.71	
ΔV_T	Hysteresis ($V_{T+} - V_{T-}$)		1.65V	0.23	0.36	0.49	V
			1.8V	0.24	0.37	0.5	
			2.5V	0.29	0.40	0.54	
			3.3V	0.34	0.44	0.55	
			5V	0.43	0.53	0.63	
			5.5V	0.44	0.57	0.66	
V_{OH}	High-level output voltage	$I_{OH} = -50\mu\text{A}$	1.65V - 5.5V	$V_{CC} - 0.1$	$V_{CC} - 0.01$		V
		$I_{OH} = -1\text{mA}$	1.65V	1.5	1.6		
		$I_{OH} = -2\text{mA}$	2.3V	2.1	2.2		
		$I_{OH} = -8\text{mA}$	3V	2.3	2.6		
		$I_{OH} = -12\text{mA}$	4.5V	3.6	4		
		$I_{OH} = -12\text{mA}$	5.5V	4.7	5		

5.5 Electrical Characteristics (continued)

Over operating free-air temperature range; typical values measured at $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
V_{OL}	Low-level output voltage	$I_{OL} = 50\mu\text{A}$	1.65V - 5.5V	0.01	0.1	V
		$I_{OL} = 1\text{mA}$	1.65V	0.01	0.1	
		$I_{OL} = 2\text{mA}$	2.3V	0.02	0.1	
		$I_{OL} = 8\text{mA}$	3V	0.05	0.3	
		$I_{OL} = 12\text{mA}$	4.5V	0.06	0.3	
		$I_{OL} = 12\text{mA}$	5.5V	0.06	0.3	
R_p	Internal pull-up or pull-down resistance		1.65V - 5.5V	1		MΩ
$I_I^{(1)}$	Input leakage current	$V_I = 5.5\text{V}$ or GND	5.5V		±200	nA
I_{OZ}	Output leakage current	$V_O = 5.5\text{V}$ or GND	5.5V		±700	nA
I_{CC}	Supply current	Standby state, $V_I^{(2)} = V_{CC}$ or GND, $I_O = 0$	5.5V	1	5	μA
I_{CC}	Supply current	Active state using low speed oscillator ⁽³⁾ , $V_I = V_{CC}$ or GND, $I_O = 0$	1.65V	6	8	μA
			2.3V	7	9	
			3V	8	11	
			4.5V	12	19	
			5.5V	16	26	
ΔI_{CC}	Supply-current change	One input, $0 < V_I < V_{CC}$, all other inputs at V_{CC} or GND, $I_O = 0$	1.65V - 5.5V		1.6	mA
C_I		$V_I = 5.5\text{V}$ or GND	5.5V	3		pF
C_O		$V_O = 5.5\text{V}$ or GND	5.5V	2.5		pF

(1) Input leakage current does not include current from internal pull-up or pull-down resistors.

(2) Inputs with internal pull-up or pull-down resistors are externally disconnected during supply current test.

(3) See *Typical Characteristics* for a table of which devices use each oscillator.

5.6 Timing Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	DESCRIPTION	CONDITION	V_{CC}	MIN	MAX	UNIT
$t_{wi}^{(1)}$	Pulse duration	$\bar{T}$ low while T low or T high while $\bar{T}$ high	1.65V	10		ns
			$1.8\text{V} \pm 0.15\text{V}$	10		
			$2.5\text{V} \pm 0.2\text{V}$	10		
			$3.3\text{V} \pm 0.3\text{V}$	10		
			$5\text{V} \pm 0.5\text{V}$	10		
$t_{startup}^{(2)}$	Startup time		1.65V - 5.5V	265		μs

(1) Minimum input pulse width to activate the timing circuitry inside the TDEL family device. Active state operation increases power consumption but may not change the output state. See *Detailed Description* section for operation details.

(2) Triggers received during device startup may be ignored.

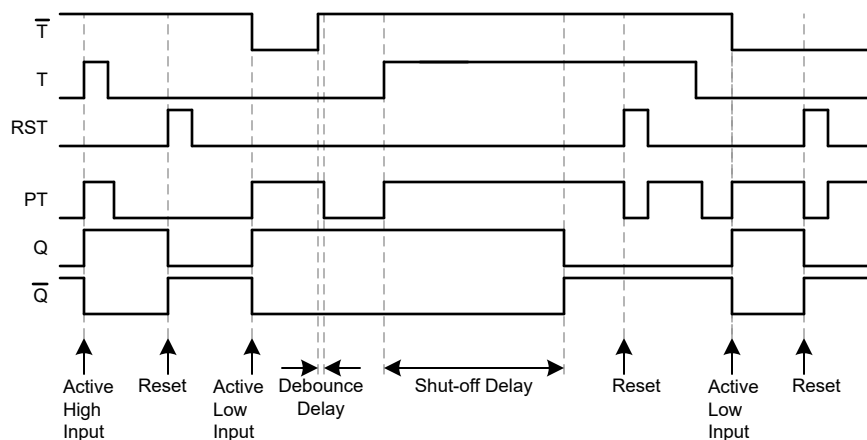


Figure 5-1. Timing Diagram

5.7 Switching Characteristics

over operating free-air temperature range; typical values measured at $T_A = 25^\circ\text{C}$ (unless otherwise noted). See *Parameter Measurement Information*.

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
$t_{pd}^{(1)}$	Any input	Any output	$C_L = 15\text{pF}$	1.65V		68	121	ns
				2.3V		58	107	
				3V		54	101	
				4.5V		51	97	
				5.5V		50	95	
			$C_L = 50\text{pF}$	1.65V		75	127	
				2.3V		63	112	
				3V		62	105	
				4.5V		56	99	
				5.5V		54	97	
t_t		Q or $\bar{Q}$	$C_L = 15\text{pF}$	1.65V		14	19	ns
				2.3V		10	14	
				3V		8	12	
				4.5V		6	9	
				5.5V		5	9	
			$C_L = 50\text{pF}$	1.65V		23	34	
				2.3V		17	25	
				3V		14	20	
				4.5V		11	16	
				5.5V		10	14	

5.7 Switching Characteristics (continued)

over operating free-air temperature range; typical values measured at $T_A = 25^\circ\text{C}$ (unless otherwise noted). See *Parameter Measurement Information*.

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
t_f		PT	$C_L = 15\text{pF}$	1.65V		10	16	ns
				2.3V		6	11	
				3V		5	9	
				4.5V		4	7	
				5.5V		4	6	
			$C_L = 50\text{pF}$	1.65V		15	22	
				2.3V		12	16	
				3V		10	12	
				4.5V		7	11	
				5.5V		7	9	
$\Delta t_{\text{delay}}^{(2)}$			$C_L = 50\text{pF}$	1.65V to 5.5V		± 1	± 10	%
$C_{pd}^{(3)}$		Q	$T = V_{CC}, \bar{T} = \text{GND}, f_i = 1\text{MHz}, C_L = 50\text{pF}$	1.65V		8		pF
				2.3V		7		
				3V		6		
				4.5V		5		
				5.5V		5		

(1) Propagation delay is only measured for signal paths that do not include internal timer-based delays.

(2) Variation in internal oscillator based delays from nominal.

(3) Power dissipation capacitance is calculated in accordance with [CMOS Power Consumption and Cpd Calculation](#).

5.8 Typical Characteristics

$T_A = 25^\circ\text{C}$ (unless otherwise noted)

Table 5-1. Delay time for each device

Device	Oscillator	Parameter	Timing Value ⁽¹⁾	
			Debounce	Shut-off
TDEL3G51000	Low speed	t_{delay}	100ms	2s
		t_{osc}	160 μs	2.56ms

(1) The delay time (t_{delay}) can additionally vary by up to $-t_{\text{osc}}$.

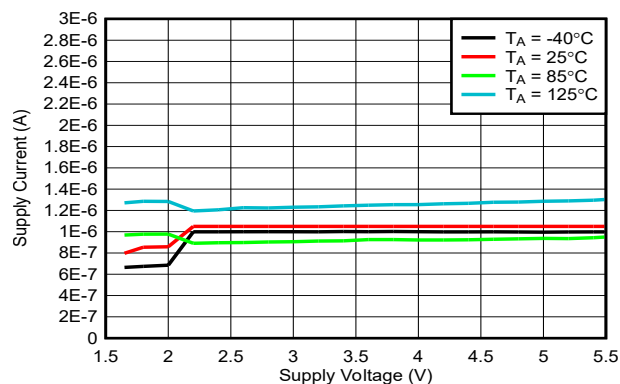


Figure 5-2. Supply Current vs Supply Voltage

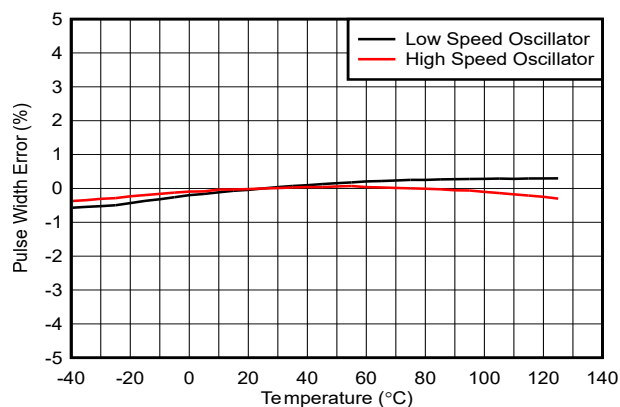


Figure 5-3. Pulse Width Error vs Temperature

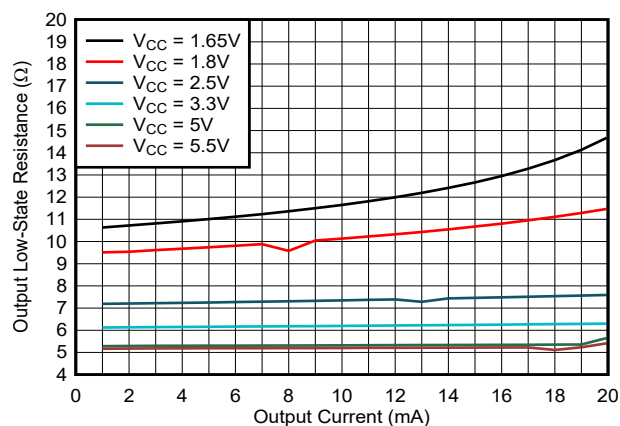


Figure 5-4. Output Low-State Resistance vs Output Current

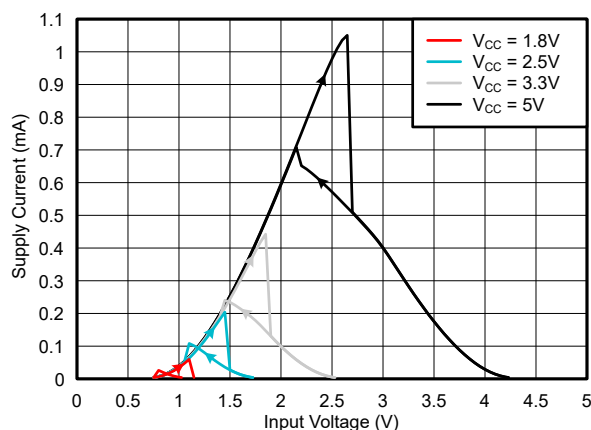


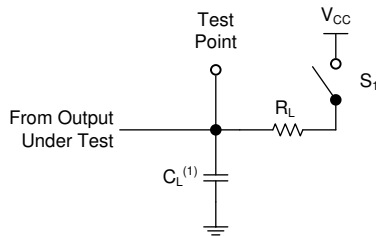
Figure 5-5. Input Voltage vs Supply Current

6 Parameter Measurement Information

Phase relationships between waveforms were chosen arbitrarily for the examples listed in the following table. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{MHz}$, $Z_O = 50\Omega$, $t_f < 2.5\text{ns}$.

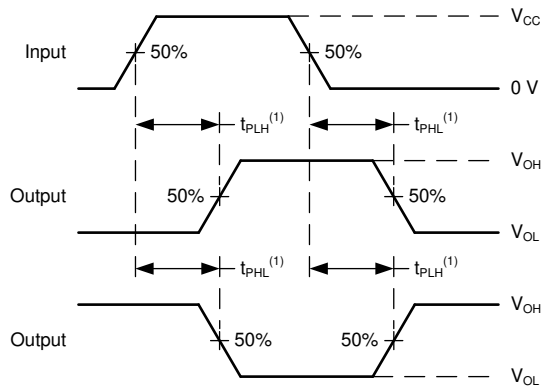
The outputs are measured individually with one input transition per measurement.

TEST	S1	R _L	C _L	ΔV	V _{CC}
t_{PLZ} , t_{PZL}	CLOSED	1k Ω	15pF, 50pF	0.15V	$\leq 2.5\text{V}$
t_{PLZ} , t_{PZL}	CLOSED	1k Ω	15pF, 50pF	0.3V	$> 2.5\text{V}$



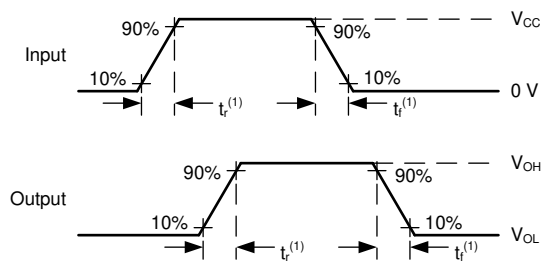
(1) C_L includes probe and test-fixture capacitance.

Figure 6-1. Load Circuit for Open-Drain Outputs



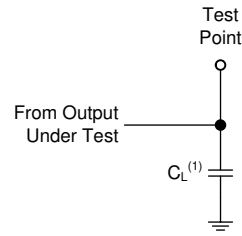
(1) The greater between t_{PLH} and t_{PHL} is the same as t_{pd} .

Figure 6-3. Voltage Waveforms Propagation Delays



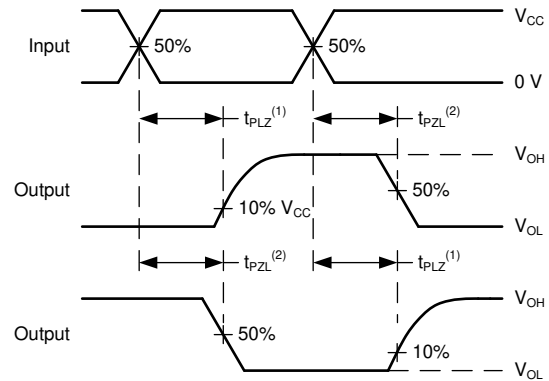
(1) The greater between t_r and t_f is the same as t_t .

Figure 6-5. Voltage Waveforms, Input and Output Transition Times



(1) C_L includes probe and test-fixture capacitance.

Figure 6-2. Load Circuit for Push-Pull Outputs



(1) t_{PLZ} is the same as t_{dis} .

(2) t_{PZL} is the same as t_{en} .

Figure 6-4. Voltage Waveforms Propagation Delays

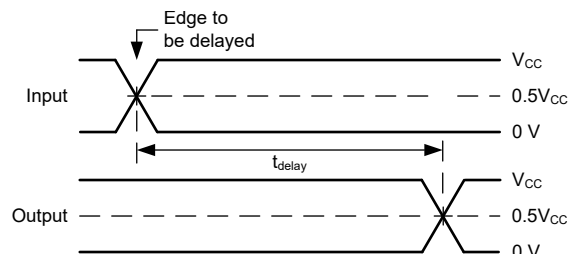


Figure 6-6. Voltage Waveforms, Edge Delay Time

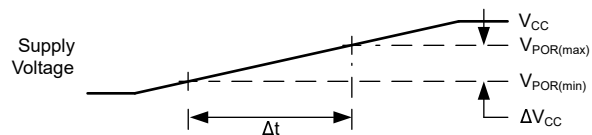


Figure 6-7. Voltage Waveforms, Supply Ramp

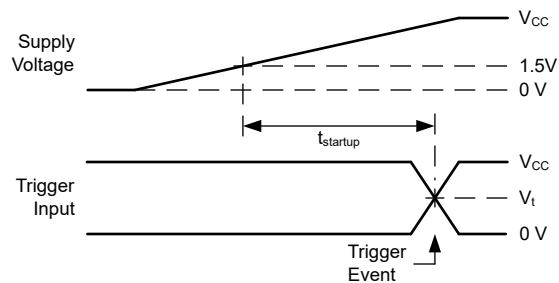


Figure 6-8. Voltage Waveforms, Startup Time

7 Detailed Description

7.1 Overview

The TDEL1G533 device is a single momentary switch interface with latching output and debounced pass-through functionality.

The device has two input options: $\bar{T}$ for active-low switches and T for active-high switches. The $\bar{T}$ input includes an internal 1M Ω pull-up resistor, allowing the input to be left disconnected when unused and eliminating the need for an external pull-up resistor. The T input includes an internal 1M Ω pull-down resistor, providing similar convenience for active-high switch applications without requiring additional external components.

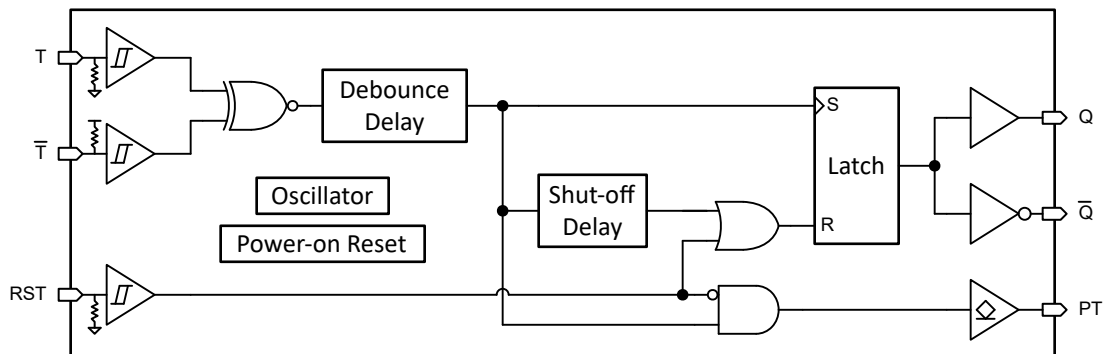
When either input is activated (a high signal at T or a low signal at $\bar{T}$), the output latches to the active state with Q high and $\bar{Q}$ low. This output state is maintained indefinitely as long as power is applied to the device.

The device includes an active-high reset input (RST) with an internal 1M Ω pull-down resistor for when the pin is unused. When RST is activated, the output immediately resets with Q returning to low and $\bar{Q}$ returning to high.

The pass-through output (PT) is an open-drain output that copies the input signal after debouncing. The positive (T) input is reproduced at the PT output with a short delay on the falling edge due to the debounce mechanism. The negative ($\bar{T}$) input is inverted at the PT output, also producing a positive waveform with a short delay on the falling edge due to the debounce mechanism. In short, either input will produce a positive output pulse. The RST signal overrides the T or $\bar{T}$ inputs, forcing the output low as long as RST is active.

During the power-up ramp, the outputs remain in a high-impedance state until the internal power-on reset circuit enables normal device operation.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Naming Convention

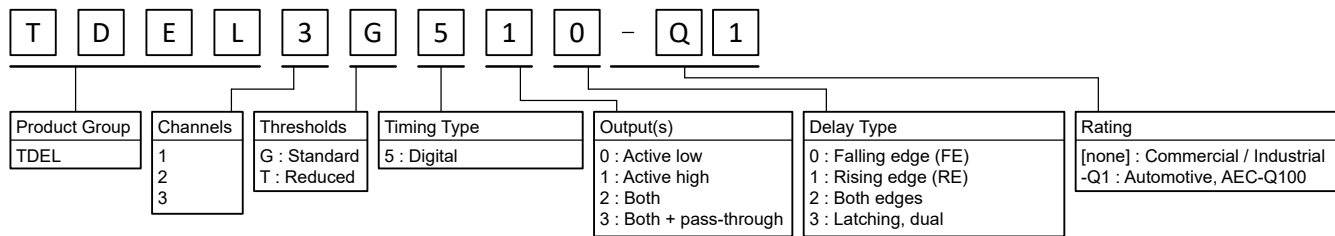


Figure 7-1. Device name meaning

7.3.2 Timing Mechanism and Accuracy

The output delay (t_{delay}) is generated by a factory-trimmed internal oscillator and binary counter. When an edge transition is detected, the oscillator activates and drives the counter until the pre-configured count is reached, at which point the output responds according to the delay type.

The maximum delay error is provided as Δt_{delay} in the *Switching Characteristics* section and includes variations due to voltage, design, manufacturing, and temperature. This variation is given as a percentage of the typical delay provided in the *Typical Characteristics* section.

7.3.3 CMOS Push-Pull Outputs

This device includes CMOS push-pull outputs. The drive capability of this device may create fast edges into light loads, so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. It is important to limit the output power of the device to avoid damage due to overcurrent. The electrical and thermal limits defined in the *Absolute Maximum Ratings* must be followed at all times.

Unused push-pull CMOS outputs must be left disconnected.

7.3.4 Open-Drain CMOS Outputs

Open-drain outputs are included in TDEL1G533. Open-drain outputs can only drive the output low. When in the high logical state, outputs are in a high-impedance state, meaning outputs neither source nor sink current (with the exception of minor leakage current as defined in the *Electrical Characteristics* table). In the high-impedance state, the output voltage is not controlled by TDEL1G533 and is dependent on external factors.

Because of the high-impedance state, an external pull-up resistor is required to define a logic high. Without a pull-up resistor, the output will float and have an undefined logic level. The resistor value depends on factors like parasitic capacitance and power consumption; typically, a 10kΩ resistor is suitable.

The drive capability of TDEL1G533 can create fast edges into light loads, so consider routing and load conditions to prevent ringing. Additionally, outputs can drive higher currents than TDEL1G533 is designed to handle continuously. Limit the device output power to avoid damage due to overcurrent. Follow the electrical and thermal limits defined in the *Absolute Maximum Ratings* at all times. See the *Recommended Operating Conditions* table for the maximum output voltage that can be externally connected to TDEL1G533.

Leave unused open-drain CMOS outputs disconnected.

7.3.5 CMOS Schmitt-Trigger Inputs

This device includes inputs with the Schmitt-trigger architecture. These inputs are high impedance and are typically modeled as a resistor in parallel with the input capacitance given in the *Electrical Characteristics* table from the input to ground. The worst case resistance is calculated with the maximum input voltage, given in the *Absolute Maximum Ratings* table, and the maximum input leakage current, given in the *Electrical Characteristics* table, using Ohm's law ($R = V \div I$).

The Schmitt-trigger input architecture provides hysteresis as defined by ΔV_T in the *Electrical Characteristics* table, which makes this device extremely tolerant to slow or noisy inputs. While the inputs can be driven much slower than standard CMOS inputs, it is still recommended to properly terminate unused inputs. Driving the inputs with slow transitioning signals will increase dynamic current consumption of the device with the maximum value per input defined as ΔI_{CC} in the *Electrical Characteristics* table. For additional information regarding Schmitt-trigger inputs, please see [Understanding Schmitt Triggers](#).

Do not leave inputs floating at any time during operation. Unused inputs must be terminated at a valid high or low voltage level. If a system is not actively driving an input at all times, then a pull-up or pull-down resistor can be added to provide a valid input voltage during these times. The resistor value will depend on multiple factors; however, a 10k Ω resistor is recommended and will typically meet all requirements.

Inputs that include internal pull-up or pull-down resistors are internally terminated to an appropriate logic level and can be left disconnected.

7.3.6 Latching Logic with Known Power-Up State

This device includes latching logic circuitry. Latching circuits commonly include D-type latches and D-type flip-flops, but include all logic circuits that act as volatile memory. In typical logic devices, the output state of each latching circuit is unknown after power is initially applied; however, this device includes an added Power On Reset (POR) circuit which sets the states of all included latching circuits during the power-up ramp prior to the device starting normal functionality.

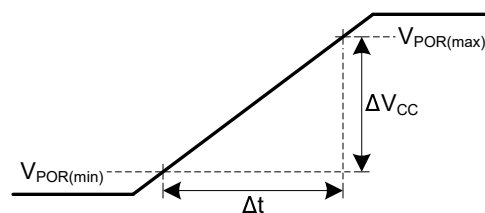


Figure 7-2. Supply (V_{CC}) Ramp Characteristics for Known Power-Up State

Figure 7-2 shows a correct supply voltage turn-on ramp and defines values used in the *Recommended Operating Conditions* and *Electrical Characteristics* tables.

Prior to starting the power-on ramp, the supply must be completely off ($V_{CC} \leq V_{POR(min)}$).

The supply voltage must ramp at a rate within the range provided in the *Recommended Operating Conditions* table.

The output state of each latching logic circuit only remains stable as long as power is applied to the device ($V_{CC} \geq V_{POR(max)}$).

Variation from these recommendations will result in the device having an unknown power-up state.

7.3.7 Clamp Diode Structure

As shown in [Figure 7-3](#), the inputs and outputs to this device have both positive and negative clamping diodes.

CAUTION

Voltages beyond the values specified in the *Absolute Maximum Ratings* table can cause damage to the device. The input and output voltage ratings can be exceeded if the input and output clamp-current ratings are observed.

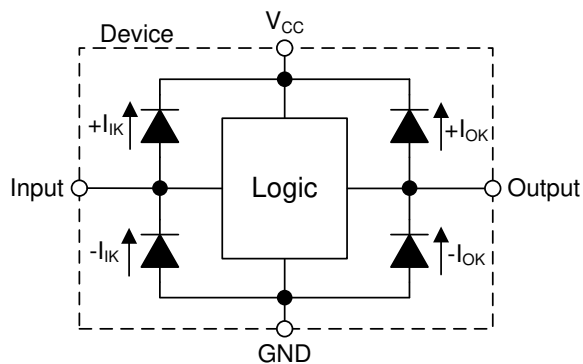


Figure 7-3. Electrical Placement of Clamping Diodes for Each Input and Output

7.4 Device Functional Modes

7.4.1 Startup Operation

The TDEL1G533 includes an internal power-on reset (POR) circuit that prevents erroneous triggers from occurring during startup. There are details on the supply ramp requirements provided in *Latching Logic with Known Power-Up State*. Normal operation can be started after the startup time (t_{startup}) has expired per the *Timing Requirements* table. While active, the POR circuit holds all outputs of the TDEL1G533 in the high-impedance state.

7.4.2 On-State Operation

The table below lists the on-state functional modes for the TDEL1G533.

Table 7-1. Function Table

INPUTS ⁽¹⁾				OUTPUTS ⁽²⁾		
RST	T	$\bar{T}$	Q'	Q	$\bar{Q}$	PT
H	X	X	X	L	H	L
L	L	H	L	L	H	L ⁽³⁾
L	L	H	H	H	L	L ⁽³⁾
L	H	L	L	L	H	L ⁽³⁾
L	H	L	H	H	L	L ⁽³⁾
L	H	H	L	H	L	Z
L	L	L	L	H	L	Z
L	H	H	H	L ⁽⁴⁾	H ⁽⁴⁾	Z
L	L	L	H	L ⁽⁴⁾	H ⁽⁴⁾	Z

- (1) H = high voltage level, L = low voltage level, Q' = previous Q state
- (2) L = driving low, H = driving high, Z = high impedance
- (3) The PT output remains in the high-impedance state after the input is released for the pre-configured debounce delay time.
- (4) The Q and $\bar{Q}$ outputs change to the shown state after the input is held in the described condition for the pre-configured shut-off delay time.

8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

The TDEL1G533 interfaces a momentary switch to a digital system, eliminating switch chatter and bounces and producing a latching output. A single button press results in a constant output signal, and holding the button for a short time results in the output resetting to the initial state. Most commonly, the output signal is used to enable the power supply for a system.

Additionally, the pass-through (PT) output and reset (RST) input allow for direct interfacing with a system controller. The pass-through output is used to allow button presses to be monitored by the system controller. The reset input allows the system controller to turn off the system without user intervention.

8.2 Typical Application

In this application, the TDEL1G533 is used with two momentary switches (S1 and S2) to provide latching enable control to a system. Both switches are functionally equivalent as inputs to the TDEL1G533; however, only one switch should be used at a time. The circuit configuration is shown in Figure 8-1.

Not shown are connections to the remainder of the system. The reset input (RST) can be connected to a digital signal source operating at the same voltage as the TDEL1G533 (V_{CC}) and is used to immediately reset the Q and $\bar{Q}$ outputs to their initial states without the need for pressing S1 or S2 and waiting for the pre-configured shut-off delay. The pass-through output (PT) is open-drain and can be connected to a pull-up voltage less than or equal to V_{CC} using resistor R1. The value of R1 is recommended to be between 1k Ω and 1M Ω .

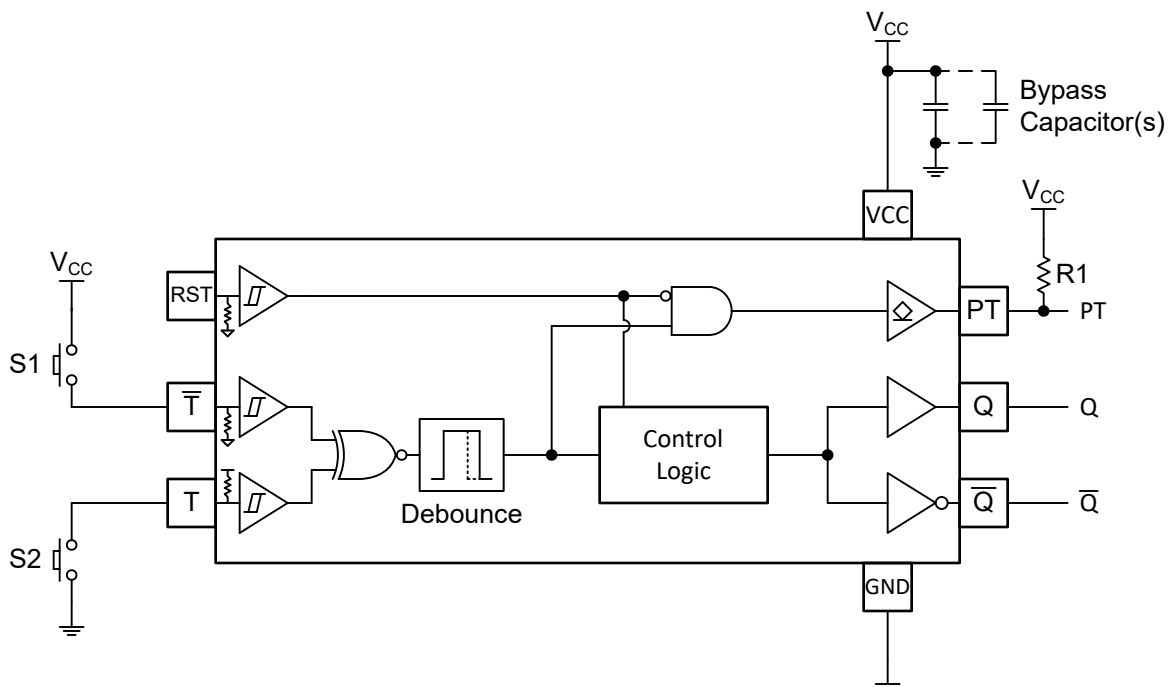


Figure 8-1. Momentary Switch Interface Schematic Using the TDEL1G533

The Q output starts low and transitions high when either switch is activated, remaining latched high indefinitely. This active-high output is commonly used to release microcontrollers from reset (by connecting to an active-low RST input) or to enable power supplies with active-low shutdown control (SHDN).

The $\bar{Q}$ output starts high and transitions low when either switch is activated, remaining latched low indefinitely. This active-low output is commonly used for system enable signals that require active-high reset (RST) inputs. The $\bar{Q}$ output is particularly useful for emergency stop applications, such as a robot kill switch, where an instant-off response to button activation is preferred.

The RST, T and $\bar{T}$ inputs all contain internal pull-up or pull-down resistors, allowing them to be left disconnected if unused. The internal resistors also eliminate the need for external resistors in the majority of cases.

8.2.1 Design Requirements

8.2.1.1 Power Considerations

Verify that the desired supply voltage is within the range specified in the *Electrical Characteristics*. The supply voltage sets the device electrical characteristics, as described in the *Electrical Characteristics* section.

The positive voltage supply must be capable of sourcing current equal to the total current to be sourced by all outputs of the TDEL1G533 plus the maximum static supply current, I_{CC} , listed in the *Electrical Characteristics*, and any transient current required for switching. The logic device can only source as much current that is provided by the positive supply source. Verify that the maximum total current through V_{CC} listed in the *Absolute Maximum Ratings* is not exceeded.

The ground must be capable of sinking current equal to the total current to be sunk by all outputs of the TDEL1G533 plus the maximum supply current, I_{CC} , listed in the *Electrical Characteristics*, and any transient current required for switching. The logic device can only sink as much current that can be sunk into the ground connection. Verify that the maximum total current through GND listed in the *Absolute Maximum Ratings* is not exceeded.

The TDEL1G533 can drive a load with a total capacitance less than or equal to 50pF while still meeting all of the datasheet specifications. Larger capacitive loads can be applied; however, do not exceed 50pF.

The TDEL1G533 can drive a load with total resistance described by $R_L \geq V_O / I_O$, with the output voltage and current defined in the *Electrical Characteristics* table with V_{OH} and V_{OL} . When outputting in the HIGH state, the output voltage in the equation is defined as the difference between the measured output voltage and the supply voltage at the V_{CC} pin.

The TDEL1G533 includes inputs with internal pullup resistors. The pullup resistors are connected to V_{CC} internally and increases the total supply current based on the input voltage (V_i) and pullup resistance (R_{pu}) per the equation: $I_{pu} = (V_{CC} - V_i) / R_{pu}$

The TDEL1G533 includes inputs with internal pulldown resistors. The pulldown resistors are connected to GND internally and increases the total ground current based on the input voltage (V_i) and pulldown resistance (R_{pd}) per the equation: $I_{pd} = V_i / R_{pd}$

Total power consumption can be calculated using the information provided in the [CMOS Power Consumption and Cpd Calculation application note](#).

Thermal increase can be calculated using the information provided in the [Thermal Characteristics of Standard Linear and Logic \(SLL\) Packages and Devices application note](#).

CAUTION

The maximum junction temperature, $T_{J(max)}$ listed in the *Absolute Maximum Ratings*, is an additional limitation to prevent damage to the device. Do not violate any values listed in the *Absolute Maximum Ratings*. These limits are provided to prevent damage to the device.

8.2.1.2 Input Considerations

Input signals must cross $V_{t-(min)}$ to be considered a logic LOW, and $V_{t+(max)}$ to be considered a logic HIGH. Do not exceed the maximum input voltage range found in the *Absolute Maximum Ratings*.

Unused inputs must be terminated to either V_{CC} or ground. The unused inputs can be directly terminated if the input is completely unused, or they can be connected with a pull-up or pull-down resistor if the input will be used sometimes, but not always. A pull-up resistor is used for a default state of HIGH, and a pull-down resistor is used for a default state of LOW. The drive current of the controller, leakage current into the TDEL1G533 (as specified in the *Electrical Characteristics*), and the desired input transition rate limits the resistor size. A 10k Ω resistor value is often used due to these factors.

The TDEL1G533 includes inputs with pull-up resistors. These inputs can be left disconnected and will be internally set to V_{CC} .

The TDEL1G533 includes inputs with pull-down resistors. These inputs can be left disconnected and will be internally set to GND.

The TDEL1G533 supports very slow input signal transition rates because it has Schmitt-Trigger inputs. See *Recommended Operating Conditions*.

Another benefit to having Schmitt-Trigger inputs is the ability to reject noise. Noise with a large enough amplitude can still cause issues. To know how much noise is too much, please refer to the $\Delta V_{T(min)}$ in the *Electrical Characteristics* table. This hysteresis value will provide the peak-to-peak limit.

Unlike what happens with standard CMOS inputs, Schmitt-Trigger inputs can be held at any valid value without causing huge increases in power consumption. The typical additional current caused by holding an input at a value other than V_{CC} or ground is plotted in the *Typical Characteristics* section.

Refer to the *Feature Description* for additional information regarding the inputs for this device.

8.2.1.3 Output Considerations

The positive supply voltage is used to produce the output HIGH voltage. Drawing current from the output will decrease the output voltage as specified by the V_{OH} specification in the *Electrical Characteristics*. The ground voltage is used to produce the output LOW voltage. Sinking current into the output will increase the output voltage as specified by the V_{OL} specification in the *Electrical Characteristics*.

Push-pull outputs that could be in opposite states, even for a very short time period, should never be connected directly together. This can cause excessive current and damage to the device.

Open-drain outputs can be connected together directly to produce a wired-AND configuration or for additional output drive strength.

Unused outputs can be left floating. Do not connect outputs directly to V_{CC} or ground.

Refer to the *Feature Description* section for additional information regarding the outputs for this device.

8.2.2 Detailed Design Procedure

1. Add a decoupling capacitor from V_{CC} to GND. The capacitor needs to be placed physically close to the device and electrically close to both the V_{CC} and GND pins. An example layout is shown in the *Layout* section.
2. Verify that the capacitive load at the output is ≤ 50 pF. Low load capacitance can be accomplished by providing short, appropriately sized traces from the TDEL1G533 to the receiving device.
3. Verify that the resistive load at the output is larger than $(V_{CC} / I_{O(max)})\Omega$. Never violate the maximum output current from the *Absolute Maximum Ratings*. Most CMOS inputs have a resistive load measured in M Ω ; much larger than the minimum calculated previously.
4. Thermal issues are rarely a concern for logic gates; however, the power consumption and thermal increase can be calculated using the steps provided in the [CMOS Power Consumption and Cpd Calculation application note](#).

8.2.3 Application Curves

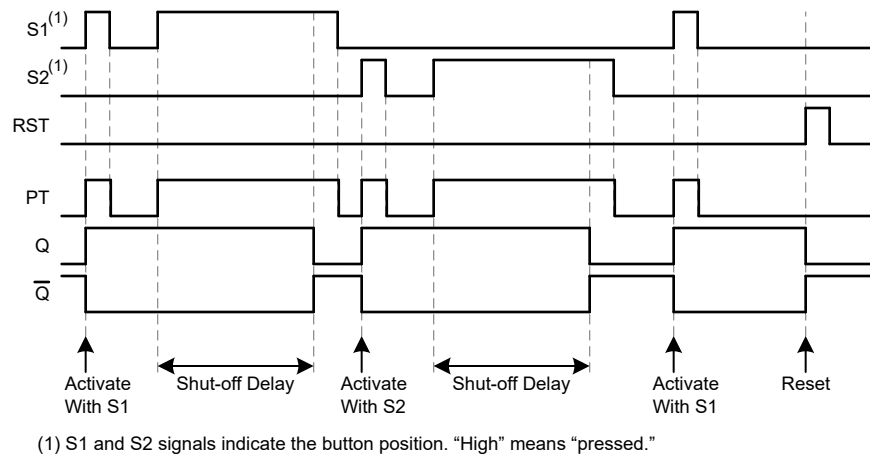


Figure 8-2. Output Timing Diagram

8.3 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating listed in the *Recommended Operating Conditions*.

During startup, the power supply should ramp within the provided power-up ramp rate range in the *Recommended Operating Conditions* table.

Each V_{CC} terminal must have a good bypass capacitor to prevent power disturbance. For normal operation of the TDEL1G533, a 0.1 μ F bypass capacitor is recommended. To reject different frequencies of noise, use multiple bypass capacitors in parallel. Capacitors with values of 0.1 μ F and 1 μ F are commonly used in parallel.

8.4 Layout

8.4.1 Layout Guidelines

- Bypass capacitor placement
 - Place near the positive supply terminal of the device
 - Provide an electrically short ground return path
 - Use wide traces to minimize impedance
 - Keep the device, capacitors, and traces on the same side of the board whenever possible
- Signal trace geometry
 - 8mil to 12mil trace width
 - Lengths less than 12cm to minimize transmission line effects
 - Avoid 90° corners for signal traces
 - Use an unbroken ground plane below signal traces
 - Flood fill areas around signal traces with ground
 - Parallel traces must be separated by at least 3x dielectric thickness
 - For traces longer than 12cm
 - Use impedance controlled traces
 - Source-terminate using a series damping resistor near the output
 - Avoid branches; buffer each signal that must branch separately

8.4.2 Layout Example

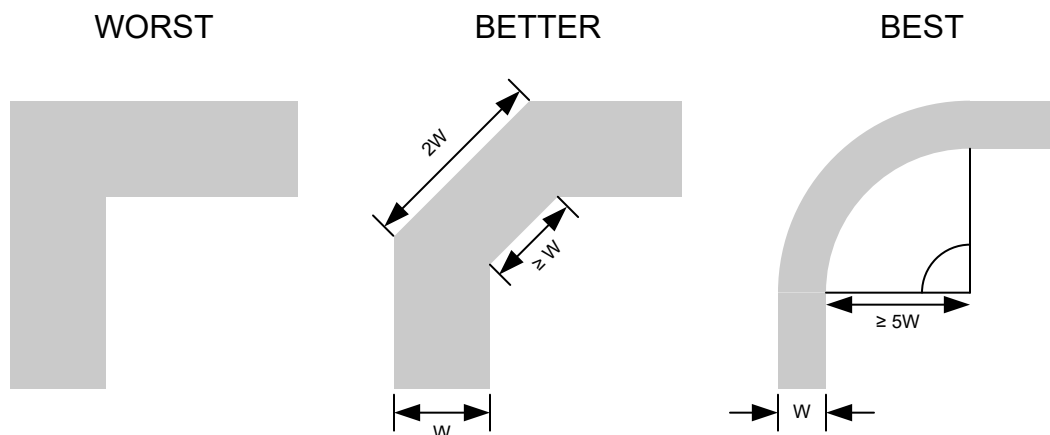


Figure 8-3. Example Trace Corners for Improved Signal Integrity

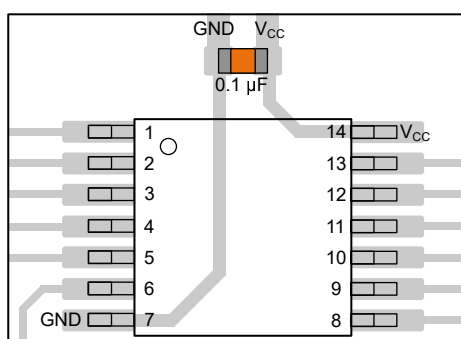


Figure 8-4. Example Bypass Capacitor Placement for TSSOP and Similar Packages

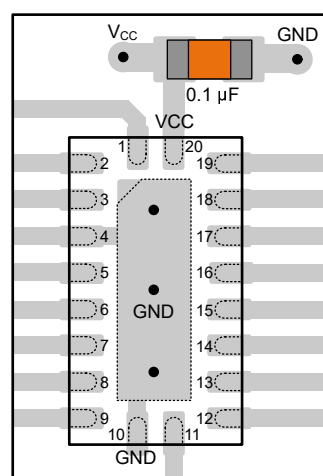


Figure 8-5. Example Bypass Capacitor Placement for WQFN and Similar Packages

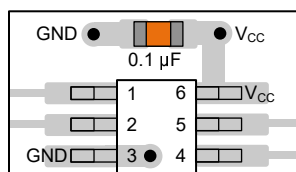


Figure 8-6. Example Bypass Capacitor Placement for SOT, SC70 and Similar Packages

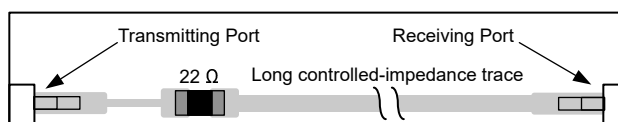


Figure 8-7. Example Damping Resistor Placement for Improved Signal Integrity

9 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

9.1 Device Support

9.1.1 Device Nomenclature

Table 9-1. Device Nomenclature

PRODUCT ⁽¹⁾	DESCRIPTION
TDEL1G533 xx yyy z	xx is the timing variant. See page 1 for a table of timing options. yyy is the package designator. z indicates the package quantity. R is for large reel (3000 pieces).

(1) For the most current package and ordering information see the Package Option Addendum at the end of this document, or visit the device product folder on www.ti.com.

9.2 Documentation Support

9.2.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [CMOS Power Consumption and \$C_{pd}\$ Calculation](#) application note
- Texas Instruments, [Designing With Logic](#) application note
- Texas Instruments, [Thermal Characteristics of Standard Linear and Logic \(SLL\) Packages and Devices](#) application note

9.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.4 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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9.5 Trademarks

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9.6 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.7 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
April 2026	*	Initial Release

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this datasheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TDEL1G53300DRLR	Active	Production	SOT-5X3 (DRL) 8	3000 LARGE T&R	-	Call TI	Level-1-260C-UNLIM	-	TDC00

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TDEL1G533 :

- Automotive : [TDEL1G533-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION



*All dimensions are nominal

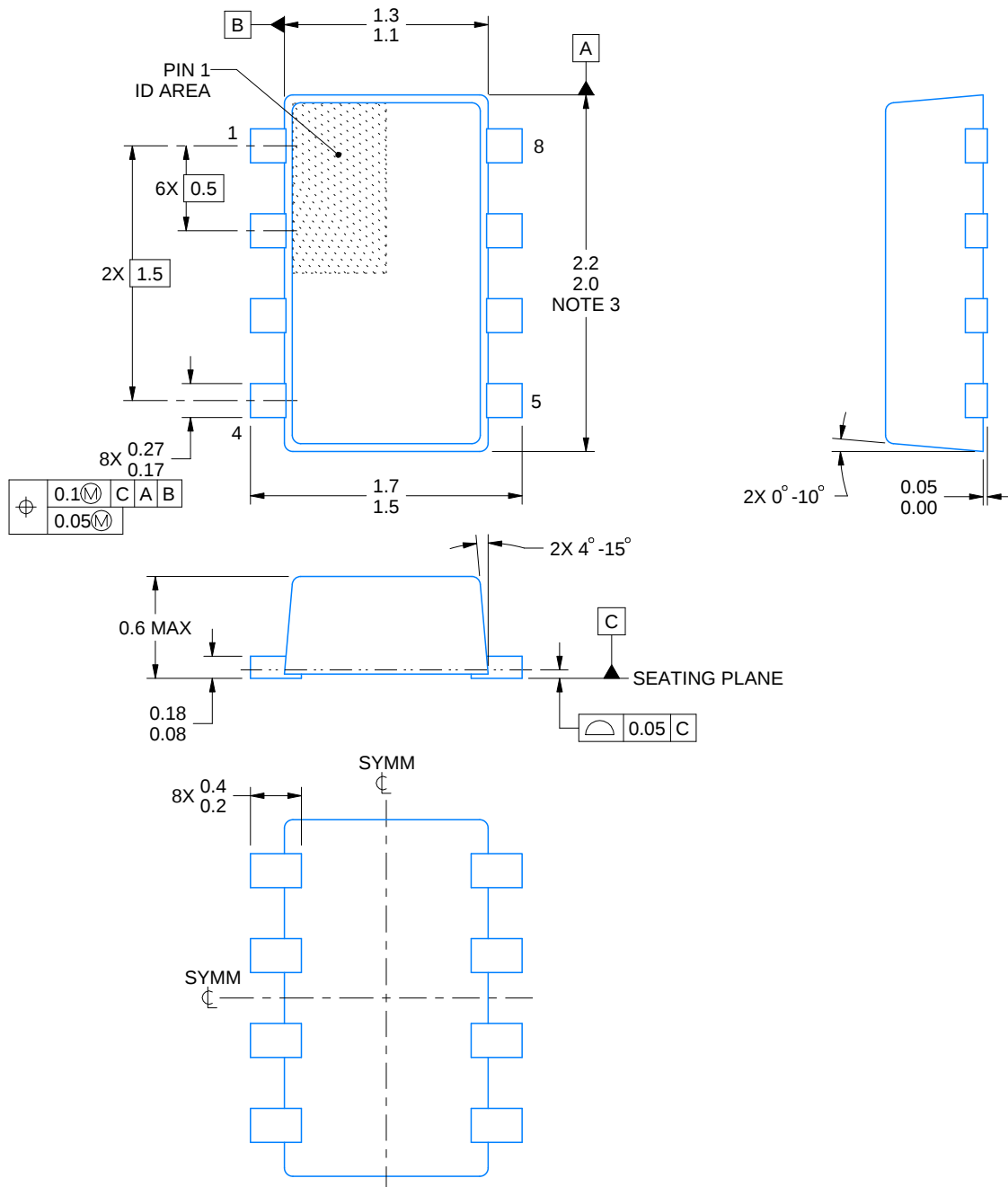
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TDEL1G53300DRLR	SOT-5X3	DRL	8	3000	180.0	8.4	2.75	1.9	0.8	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TDEL1G53300DRLR	SOT-5X3	DRL	8	3000	210.0	185.0	35.0



4224486/G 11/2024

NOTES:

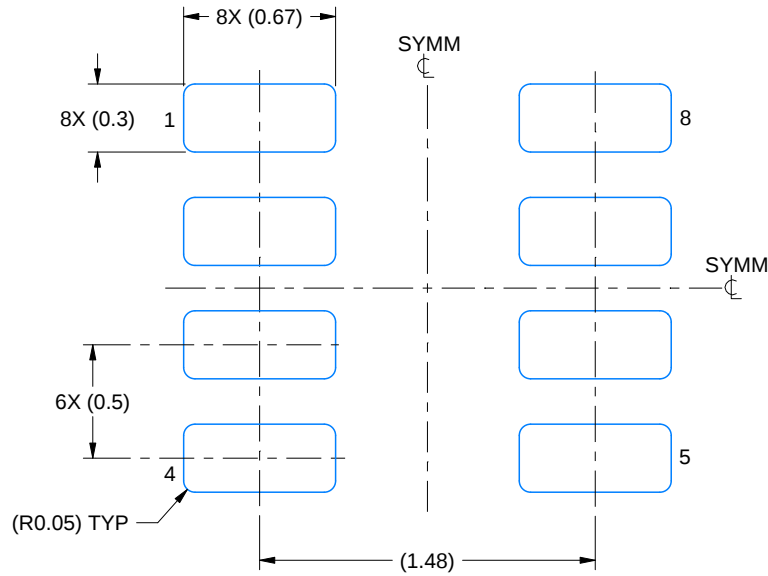
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC Registration MO-293, Variation UDAD

EXAMPLE BOARD LAYOUT

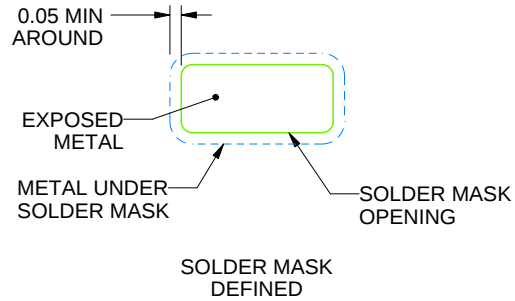
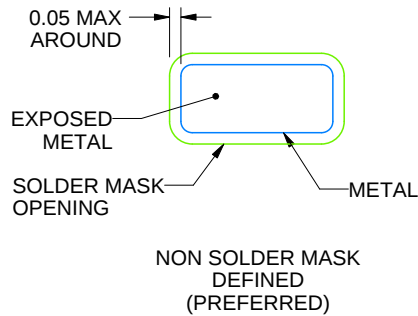
DRL0008A

SOT-5X3 - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:30X



SOLDERMASK DETAILS

4224486/G 11/2024

NOTES: (continued)

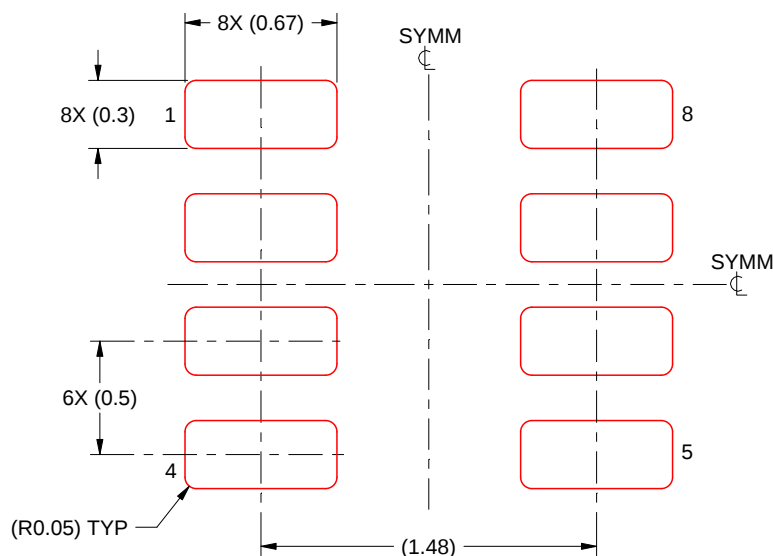
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
7. Land pattern design aligns to IPC-610, Bottom Termination Component (BTC) solder joint inspection criteria.

EXAMPLE STENCIL DESIGN

DRL0008A

SOT-5X3 - 0.6 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:30X

4224486/G 11/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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